

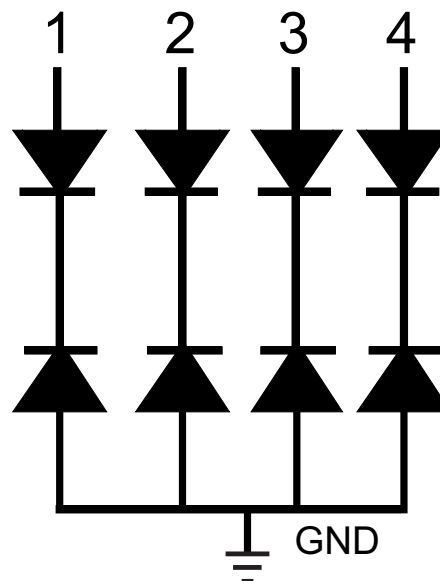
带有 15kV 接触放电保护和超低钳位电压的 4 通道双向低电容值静电放电保护 (ESD) 器件

查询样品: [TPD4E101](#)

特性

- 为低压输入输出 (IO) 接口提供系统级的 ESD 保护
- IEC 61000-4-2 级别 4
 - $\pm 15\text{kV}$ (空气放电)
 - $\pm 15\text{kV}$ (接触放电)
- IO 电容值 $< 5\text{pF}$
- 超低泄漏电流
- 超低钳位电压
- 工业温度范围: -40°C 至 125°C
- 节省空间的微型四方扁平无引线 (μQFN) 封装

器件电路原理图



应用范围

- 手机
- 电子书
- 便携式媒体播放器
- 数码摄像机
- 平板个人电脑
- 机顶盒

说明

TPD4E101 是一款采用超小型封装的四通道 ESD 保护器件。它是业界最小的 4 通道 ESD 保护器件。较大的引脚间距帮助节省了印刷电路板 (PCB) 的制造成本。此器件提供与 IEC61000-4-2 兼容的高达 15kV 接触放电保护。此器件具有 ESD 钳位电路, 此电路的背对背二极管支持单极/双向信号。低线路电容使得此器件适合于广泛的支持数据速率可高达 700Mbps 的应用。在便携式应用方面的典型应用领域包括:

- 音频线路 (麦克风、耳机和扬声器电话)
- SD 接口
- SIM 接口
- 辅助键盘或者其它按钮



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To request a full datasheet, please send an email to:

lpd-marketing@list.ti.com

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPD4E101DPWR	Active	Production	X2SON (DPW) 4	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	A1
TPD4E101DPWR.B	Active	Production	X2SON (DPW) 4	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	A1

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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GENERIC PACKAGE VIEW

DPW 4

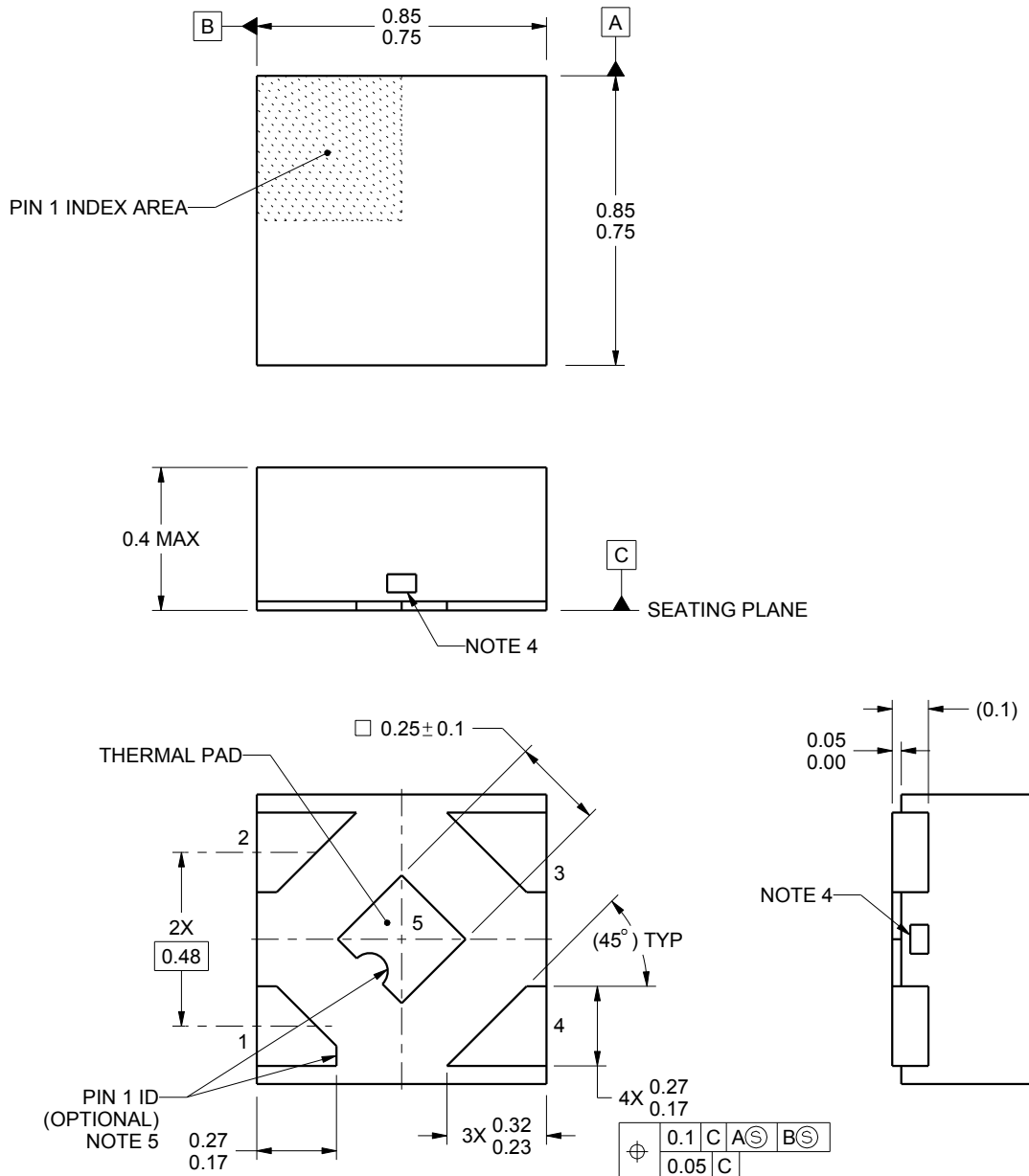
X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

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NOTES:

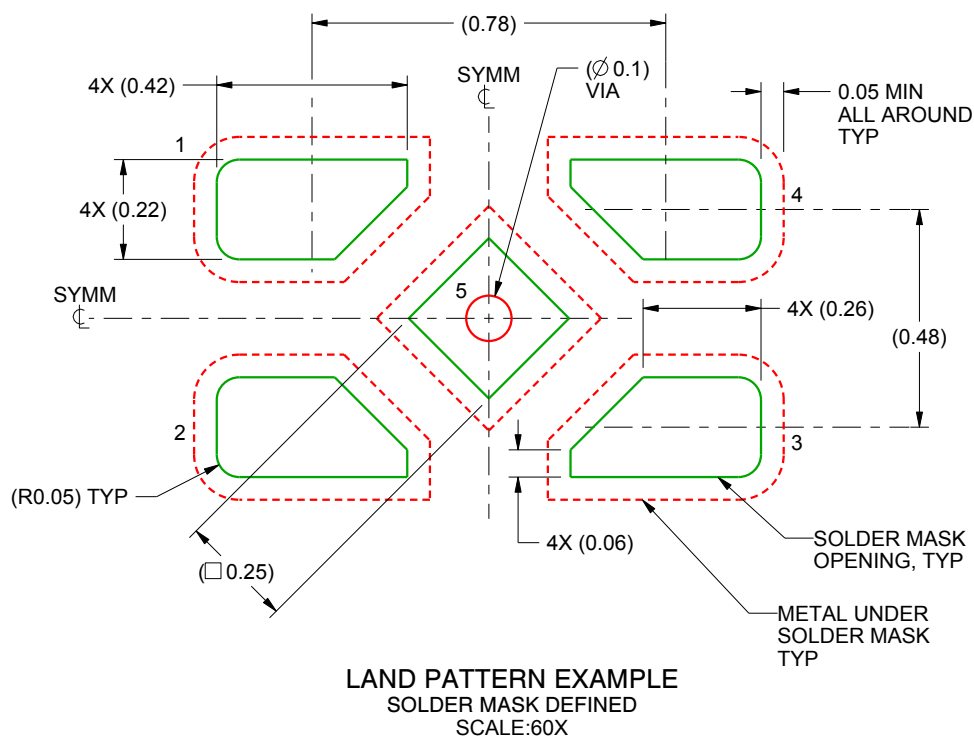
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. The size and shape of this feature may vary.
5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.

EXAMPLE BOARD LAYOUT

DPW0004A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



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NOTES: (continued)

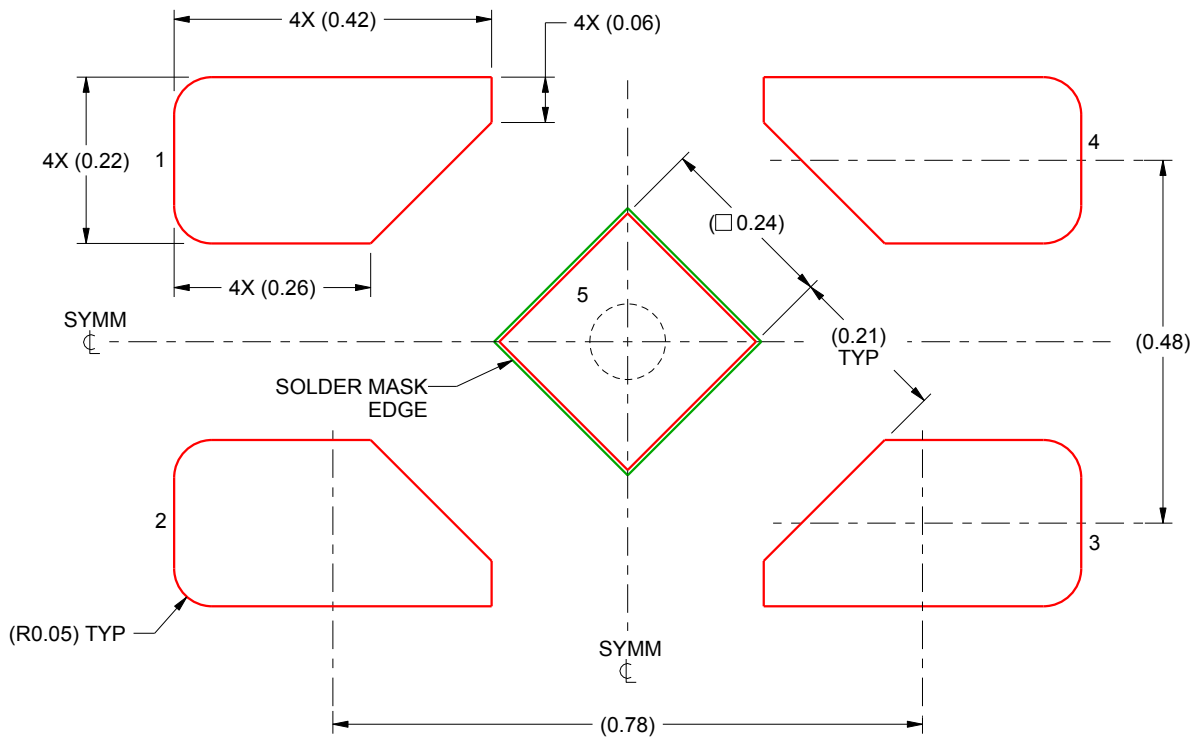
6. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
7. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

DPW0004A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 5:
92% PRINTED SOLDER COVERAGE BY AREA
SCALE:100X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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